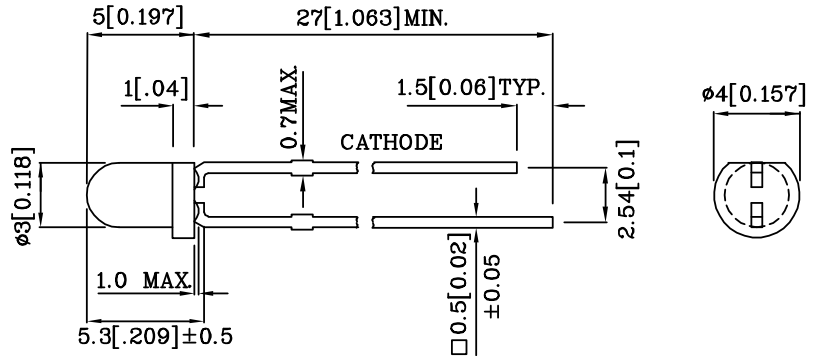


**Features**

- T-1 PACKAGE WITH RECTANGULAR BASE.
- WITH BUILT-IN BLINKING IC.
- OPERATION VOLTAGE FROM 3.5V TO 14V.
- BLINKING FREQUENCY FROM 3.0Hz TO 1.5Hz.
- RoHS COMPLIANT.



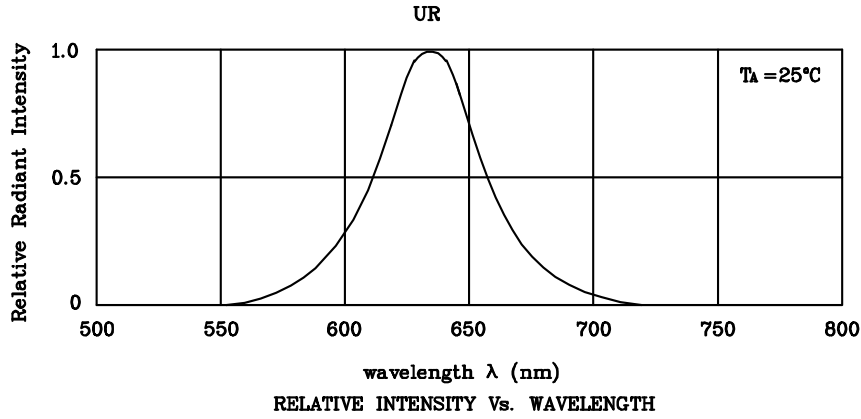
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.

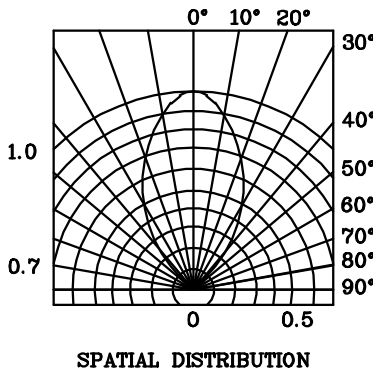
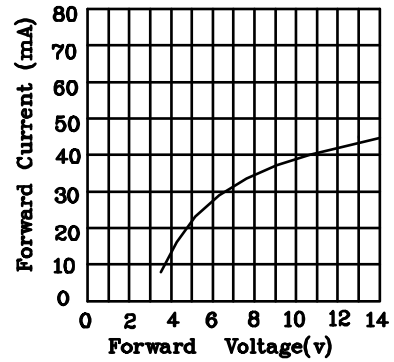
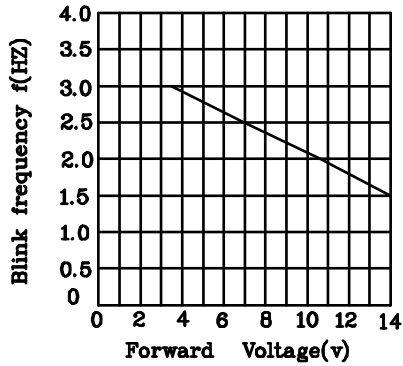
Absolute Maximum Ratings (TA=25°C)		UR (GaAsP/GaP)	Unit
Reverse Voltage	V <sub>R</sub>	0.5	V
Forward Voltage	V <sub>F</sub>	14	V
Power Dissipation	P <sub>T</sub>	310	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +70	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (TA=25°C)		UR (GaAsP/GaP)	Unit
Forward Current (Min.) (V <sub>F</sub> =3.5V)	I <sub>F</sub>	8	mA
Forward Current (Typ.) (V <sub>R</sub> =5V)	I <sub>F</sub>	22	mA
Supply Current V <sub>F</sub> =3.5V	I <sub>SON</sub>	8	mA
Supply Current V <sub>F</sub> =14V	I <sub>SON</sub>	44	mA
Blink Frequency V <sub>F</sub> =3.5V	f	3	Hz
Blink Frequency V <sub>F</sub> =14V	f	1.5	Hz
Wavelength of Peak Emission	λ <sub>P</sub>	627	nm
Wavelength of Dominant Emission	λ <sub>D</sub>	625	nm
Spectral Line Half-Width	Δλ	45	nm

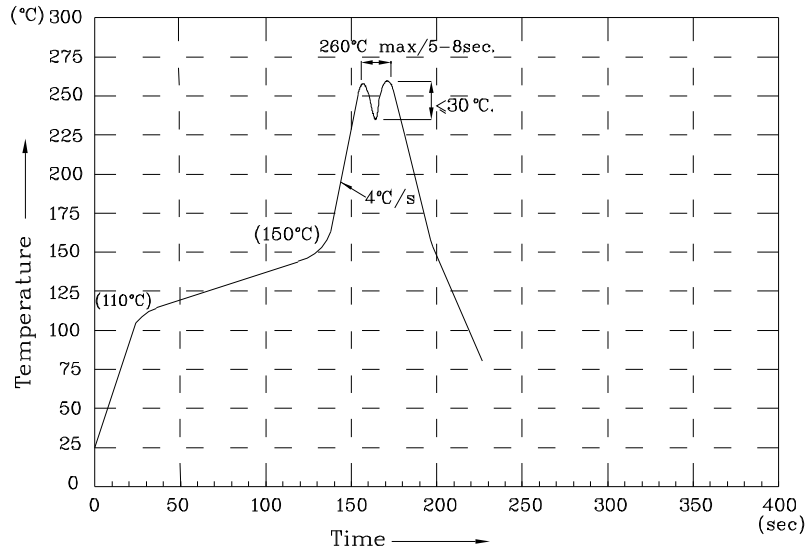
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (V= 9V) mcd		Wavelength nm λ <sub>P</sub>	Viewing Angle 2θ 1/2
				min.	typ.		
XBUR34D	Red	GaAsP/GaP	Red Diffused	12	19	627	60°
Published Date : MAY 30,2005      Drawing No : XDSA2642      V3      Checked : B.L.LIU      P.1/3							



❖ UR



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85 degree°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.No more than once.